



THE UNITED STATES PATENT AND TRADEMARK OFFICE

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APPLICANT: Keith E. FOGEL et al.      CONFIRM. NO.: 6557  
SERIAL NO.: 10/815,103      ART UNIT: 2826  
FILED: 03/31/2004      EXAMINER: L. ANDUJAR  
TITLE: INTERCONNECTIONS FOR FLIP-CHIP USING LEAD-FREE  
SOLDERS AND HAVING REACTION BARRIER LAYERS  
ATTORNEY DOCKET NO.: YOR920030190US1

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

Responsive to the final Office Action of October 3,  
2007, please reconsider and allow this application in view  
of the following:

|                                     |        |
|-------------------------------------|--------|
| Amendments to the Specification     | Page 2 |
| Listing of and Amendments to Claims | Page 3 |
| Remarks                             | Page 7 |

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January 3, 2008  
Date

David Aher  
Name of Person Making Deposit